

ABSTRACT OF THE DISCLOSURE

An image sensor and a method for manufacturing the same. The image sensor includes a substrate, a photosensitive chip mounted to the substrate, a plurality of wires for electrically connecting the photosensitive chip to the substrate, a frame layer mounted to the substrate to surround the photosensitive chip. And a transparent layer is fixed and encapsulated by the frame layer such that the photosensitive chip may receive optical signals passing through the transparent layer.